

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Nawalage Florence COORAY

Serial No.

Group Art Unit:

Confirmation No.

Filed: June 28, 2001

Examiner:

For: THERMOSETTING FLUORINATED DIELECTRICS AND MULTILAYER CIRCUIT
BOARDS

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Before calculation of the filing fee for the subject application, please amend the
above-identified application as follows:

IN THE CLAIMS:

Please AMEND the pending claims and ADD new claims * in accordance with the
following:

3. (AS ONCE AMENDED HEREIN) A dielectric film obtained by heat curing a
thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1.

4. (AS ONCE AMENDED HEREIN) A process for producing a dielectric film
comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer
according to claim 1.

6. (AS NEW HEREIN) A dielectric film obtained by heat curing a thermally curable
fluorinated o-aminophenol polymer or oligomer according to claim 2.

7. (AS NEW HEREIN) A process for producing a dielectric film comprising heat
curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 2.

09922603 062801
108290 00922603

Serial No.:

8. (AS NEW HEREIN) A multilayer circuit board comprising a dielectric film according to claim 6.

REMARKS


This Preliminary Amendment is submitted to delete multiple dependent claims as presented in the concurrently filed subject application. No new matter is presented.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

STAAS & HALSEY LLP

Date: June 28, 2001

By: 
H. J. Staas
Registration No. 22,010

700 Eleventh Street, NW, Suite 500
Washington, D.C. 20001
(202) 434-1500

IN THE CLAIMS:

3. (ONCE AMENDED) A dielectric film obtained by heat curing a thermally curable substituted o-aminophenol polymer or oligomer according to claim 1 [or 2].

Please ADD the following claims:

7. (NEW) A process for producing a dielectric film comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 2.

3